| ASSOCIATION CONNECTING                      | Material Composi<br>© Copyright 2005. IPC,<br>international and Pan-Ar | Bannockb       | urn, Illinois. A               | ll rights reserved un ntions. | nder both               | This docume<br>level parts, t                                     | ent is a declaration                      | ion of the s<br>encompasse | ubstances<br>es all lower  | within the manufactur<br>r level materials for w | rer listed i<br>hich the r      | tem. Note: if<br>nanufacturer | f the item is an as<br>has engineering | sembly with low responsibility. |
|---|--|----------------|--------------------------------|-------------------------------|-------------------------|---|---|----------------------------|----------------------------|--|---------------------------------|-------------------------------|--|---------------------------------|
| 1752-21.1                                   |  |                |                                |                               | Form Type<br>Distribute | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Mater |   |                            |                            |  | ials and Mfg Information        |                               |  |                                 |
| Supplier Inform                             | ation  |                |                                |                               |                         |   | · · ·                                     |                            |                            |  |                                 |                               |  |                                 |
| Company name*                               |  |                | Company unique ID              |                               |                         | Unique ID Authority   |   |                            |                            | Response Date*                                   |                                 |                               |  |                                 |
| onsemi                                      |  |                |                                |                               |                         |   |   |                            |                            |  | 2024-05-03                      |                               |  |                                 |
| Contact Name                                |  |                | Title - Contact                |                               |                         |   | Phone - Contact*                          |                            |                            |  | Email - Contact*                |                               |  |                                 |
| Product-Env-Stewards                        |  |                | Product Enviro Compliance      |                               |                         |   | NA  |                            |                            |  | Product-Env-Stewards@onsemi.com |                               |  |                                 |
| Authorized Representative*                  |  |                | Title - Representative         |                               |                         |   | Phone - Representative*                   |                            |                            | Email - Representative*                          |                                 |                               |  |                                 |
| Product-Env-Stewards                        |  |                | Product Enviro Compliance      |                               |                         |   | NA  |                            |                            |  | Product-Env-Stewards@onsemi.com |                               |  |                                 |
| Requester                                   | Requester Item Number Mfr Iten   |                | n Number Mfr Item Name         |                               |                         |   | Effective Date Version Manufacturing Site |                            | Manufacturing Site         |  | Weight*                         | UOM                           | Unit Type                              |                                 |
|   |  | QT6810 RI      |                                | RFIC 2.4 GHz                  |                         |   | 2024-05-03                                |                            | ŀ                          | KR9  |                                 | 96.499                        | mg                                     | Each                            |
| /Ianufacturing I                            | Proccess Information   | n              |                                |                               |                         |   | -   | -                          |                            |  | 1                               |                               |  | l                               |
| Terminal Plating / Grid Array Material Term |  | erminal Base A | minal Base Alloy J-STD-020 MSL |                               | L Rating                | Peak Process Body Temperate                                       |   | emperatur                  | ure Max Time at Peak Tempe |  | ture Numb                       | er of Reflow Cyc              | cles                                   |                                 |
| SnAgCu CU A                                 |  |                | U Alloy 3                      |                               |                         |   | 260                                       |                            | C                          | 30   | secor                           | ids 3                         |  |                                 |
| omments                                     |  |                |                                |                               |                         |   |   |                            |                            |  |                                 |                               |  |                                 |
| <b>FTENTION: MSL</b>                        | 3 Rated item requires Ba   | ake and D      | ry Pack (after                 | electrical test)              |                         |   |   |                            |                            |  |                                 |                               |  |                                 |
| or more informatio                          | n regarding material con   | nposition      | please refer to                | page 3                        |                         |   |   |                            |                            |  |                                 |                               |  |                                 |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl othalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material      | Weight | Unit of Measure | Level    | Substance  | CAS              | Exempt | Weight  | Unit of Measure |
|---------------------------|--------|-----------------|----------|--|------------------|--------|---------|-----------------|
| Die                       | 10.0   | mg              | Supplier | Silicon (Si)   | 7440-21-3        |        | 10      | mg              |
| Mold Compound-Black       | 35.49  | mg              | Supplier | Carbon Black (C)   | 1333-86-4        |        | 0.1775  | mg              |
|                           |        |                 | Supplier | Fused Silica (SiO2)  | 60676-86-0       |        | 31.4087 | mg              |
|                           |        |                 | Supplier | Ortho-Cresol Novolac Resin                                   | 29690-82-2       |        | 1.952   | mg              |
|                           |        |                 | Supplier | Phenolic Resin (Novolac)                                     | 9003-35-4        |        | 1.952   | mg              |
| Solder Ball               | 10.49  | mg              | Supplier | Silver (Ag)  | 7440-22-4        |        | 0.3147  | mg              |
|                           |        |                 | Supplier | Tin (Sn)   | 7440-31-5        |        | 10.1228 | mg              |
|                           |        |                 | Supplier | Copper (Cu)  | 7440-50-8        |        | 0.0524  | mg              |
| Solder Mask               | 3.325  | mg              | Supplier | Talc   | 14807-96-6       |        | 0.1663  | mg              |
|                           |        |                 | Supplier | Naphthalene  | 91-20-3          |        | 0.0665  | mg              |
|                           |        |                 | Supplier | Phosphinoxide Derivative                                     | Proprietary Data |        | 0.1663  | mg              |
|                           |        |                 | Supplier | 2-(2-methoxypropoxy)propanol                                 | 34590-94-8       |        | 0.399   | mg              |
|                           |        |                 | Supplier | 4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-<br>tetramethylbiphenyl | 85954-11-6       |        | 0.7648  | mg              |
|                           |        |                 | Supplier | Solvent Naphtha (Solvent oil)                                | 64742-94-5       |        | 0.4655  | mg              |
|                           |        |                 | Supplier | Barium Sulfate (BaSO4)                                       | 7727-43-7        |        | 1.2967  | mg              |
| ubstrate Copper Foil      | 1.26   | mg              | Supplier | Copper (Cu)  | 7440-50-8        |        | 1.26    | mg              |
| Substrate - Core Material | 13.94  | mg              |          | Epoxy resin  | proprietary data |        | 3.0208  | mg              |
|                           |        |                 | Supplier | Fiber Glass (SiO2)   | 65997-17-3       |        | 10.9192 | mg              |
| Substrate Plating-Cu      | 21.994 | mg              | Supplier | Copper (Cu)  | 7440-50-8        |        | 21.994  | mg              |